

CLAIMS

1. A tape for electronic device packaging, comprising:
a pressure-sensitive adhesive tape having a base film and a pressure-sensitive adhesive layer; and
a laminate of an adhesive layer and a metal layer provided by laminating on a surface of the pressure-sensitive adhesive layer, the surface being on the opposite side of the base film,
the pressure-sensitive adhesive layer, the adhesive layer, and the metal layer are provided in this order,
wherein the adhesive layer has a peeling force of 0.3 N or more against the metal layer at 23°C, a peeling angle of 180° and a linear velocity of 300 mm/min in the B-stage, and
the metal layer has a tensile strength of 350 MPa or higher.
2. The tape for electronic device packaging according to claim 1, wherein the metal layer contains copper or aluminum.
3. The tape for electronic device packaging according to claim 1 or 2, wherein the metal layer has a copper content of 99.95% or less.
4. The tape for electronic device packaging according to any one of claims 1 to 3, wherein the metal layer is a copper alloy foil or an aluminum alloy foil.

5. The tape for electronic device packaging according to any one of claims 1 to 4, wherein the metal layer comprises an alloy including copper and one kind or two or more kinds selected from the group consisting of nickel, chromium, zirconium, zinc, tin, titanium, silicon, iron, manganese, magnesium, phosphorus, and cobalt.

6. The tape for electronic device packaging according to any one of claims 1 to 4, wherein the metal layer comprises an alloy including aluminum and one kind or two or more kinds selected from the group consisting of nickel, chromium, zirconium, zinc, tin, magnesium, copper, manganese, titanium, silicon, iron, and cobalt.

7. The tape for electronic device packaging according to any one of claims 1 to 4, wherein the metal layer comprises stainless steel.

8. The tape for electronic device packaging according to any one of claims 1 to 7, wherein the metal layer has a thermal conductivity of 5 W/(m·K) or higher.

9. The tape for electronic device packaging according to any one of claims 1 to 8, wherein the adhesive layer contains (A) an epoxy resin, (B) a curing agent, (C) an acrylic resin or a phenoxy resin, and (D) a surface-treated inorganic filler.

10. The tape for electronic device packaging according to any one of claims 1 to 9, wherein the pressure-sensitive adhesive layer contains an acrylic polymer configured to include an acrylic acid ester represented by the formula: $\text{CH}_2=\text{CHCOOR}$ (wherein R represents an alkyl group having 4 to 18 carbon atoms), a hydroxyl group-containing monomer, and an isocyanate compound having a radical reactive carbon-carbon double bond in the molecule.